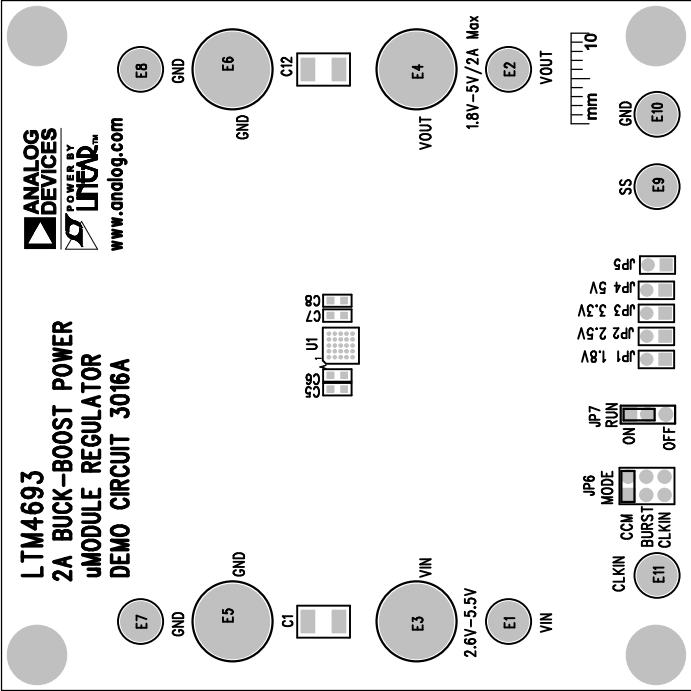
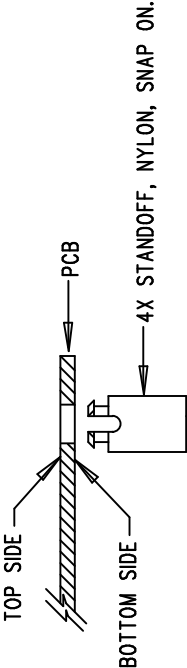




REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	2	Prod	Ling J.
			DATE
			1-14-21

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 ANALOG DEVICES  POWER BY LINEAR™ 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.analog.com	
PCB DES.	HZ	FOR ARI CUSTOMER USE ONLY	
APP ENG.	Ling J.	TITLE: TOP ASSEMBLY DRAWING	
		1A BUCK-BOOST POWER MODULE REGULATOR	
		SIZE	IC NO. LTM4693EV REV. 2
		N/A	DEMO CIRCUIT 3016A
SCALE = NONE		FILENAME: DC3016A2.PCB SHT 1 OF 2	